

## II. CORRECTED SPECIFICATION

The disclosure was objected to because of the lack of part numbers in the description and drawings. Corrected drawings have now been submitted and the following amendments to the Specification are requested to correct the objected to deficiency in the disclosure. It should be noted that no new matter is added to the Specification by way of the proposed amendments.

1. Please amend the Specifications by replacing the Brief Description of the Drawings with the following new Brief Description of the Drawings:

### Brief Description of the Drawings

[0036] Figure ~~A~~ 1 is a cross sectional view of the heat sink system according to the preferred embodiment of the present invention.

[0038] Figures ~~B~~ 2a and 2b ~~are is a perspective~~ an exploded view of the heat sink system according to the preferred embodiment of the present invention.

2. Please amend the Specifications by replacing the Detailed Description of the Invention with the following new Detailed Description of the Invention:

### Detailed Description of the Invention

[0040] The preferred embodiment of the present invention will be described with reference to Figures ~~A~~ 2a and 2b.

[0042] In Figures ~~A~~ 2a and 2b, ~~a cross-section~~ an exploded view of the invention is seen. The component to be cooled(102) is isolated to a printed circuit board(103) separated from those components which need not be cooled but are intended to be protected from dirt, dust and

contaminants. The component to be cooled(102) is attached to a heat sink(106) by means of spacers (104). The spacers(104) may be made of aluminum, copper or other thermal conducting material. The spacers(104) create a space between the component to be cooled(102) and the heat sink(106).

[0048] The heat sink(106) consists of a base with a top and bottom surface. The spacers (104) are connected to the top surface of the heat sink(106). Radiating fins project from the bottom surface of the heat sink base(106) and are cooled by external air. The base of the heat sink(106) has a first opening off center of sufficient size for a motor and fan assembly(105) to be installed. A motor is mounted to the opening. A fan is operatively connected to the motor such that air is forced by the fan into the space created by the spacer(104) between the base(106) and the component to be cooled(102). The heat sink base(106) also has a second opening, off center and opposite of center to the first opening, through which air may be exhausted to the exterior environment.

[0056] The fan(105) when operating should be installed such that external air is drawn into the first opening created in the base of the heat sink(106) and flows over the top base of the heat sink(106) through the space created by the spacers(104). The heated air is then exhausted through the second opening.

[0059] A shield(101) is installed around the printed circuit board(103) upon which is mounted the part to be cooled(102). The shield (101) should have at least one side wall and a top wall. In the preferred embodiment there are four side walls with each side wall connected to the top wall and the heat sink(106).

### III. CONCLUSION

It is believed that the new drawings are in conformance with the USPTO requirements and